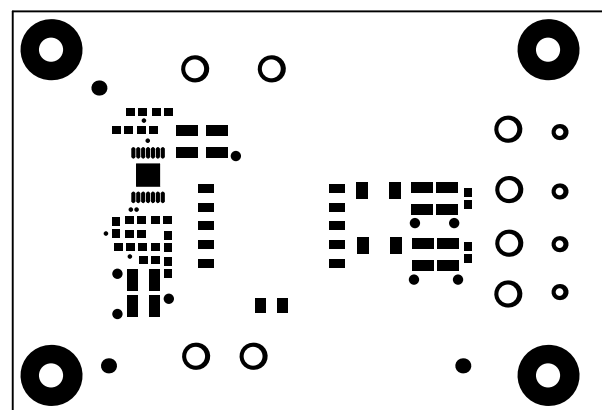
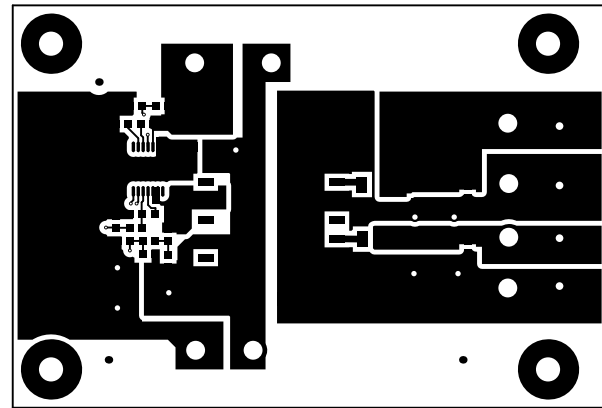


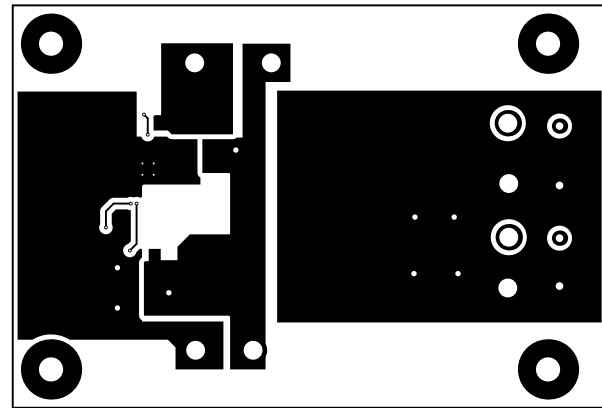
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP20330		
PLOT NAME = Top Overlay	GENERATED : 12/19/2016 3:40:38 PM	TEXAS INSTRUMENTS	



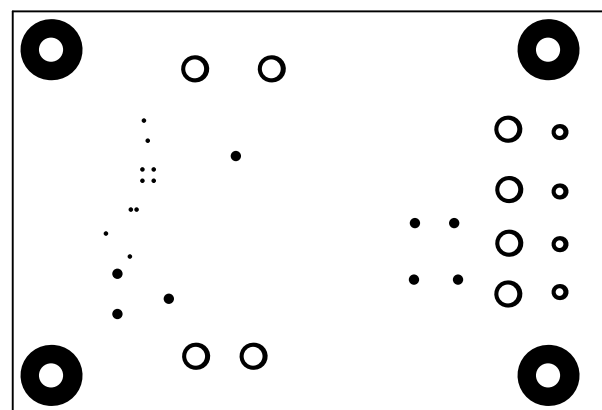
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20330		
PLOT NAME = Top Solder Mask	GENERATED : 12/19/2016 3:40:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20330		
PLOT NAME = Top Layer	GENERATED : 12/19/2016 3:40:42 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20330		
PLOT NAME = Bottom Layer	GENERATED : 12/19/2016 3:40:44 PM	TEXAS INSTRUMENTS	

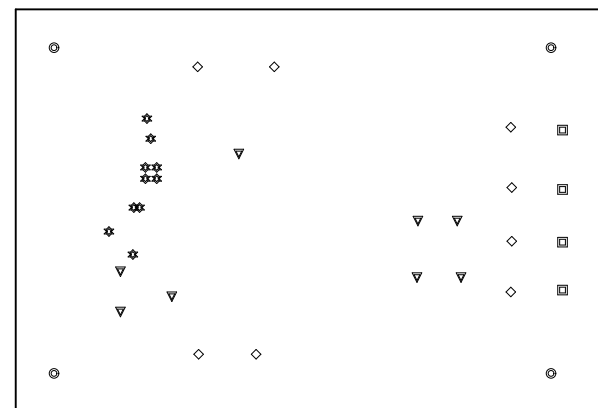


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20330		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/19/2016 3:40:46 PM	TEXAS INSTRUMENTS	

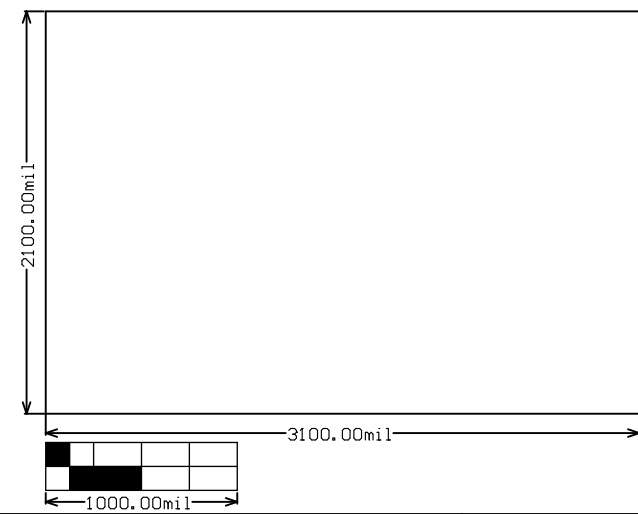


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP20330		
PLOT NAME = Bottom Overlay	GENERATED : 12/19/2016 3:40:47 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✱	10	10.00mil (0.254mm)	PTH	Round
▽	8	28.00mil (0.711mm)	PTH	Round
■	4	40.00mil (1.016mm)	PTH	Round
◇	8	98.43mil (2.500mm)	PTH	Round
⊙	4	125.98mil (3.200mm)	PTH	Round
	34 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20330		
PLOT NAME = Drill Drawing	GENERATED : 12/19/2016 3:40:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20330	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20330		
PLOT NAME = Board Dimensions	GENERATED : 12/19/2016 3:40:49 PM	TEXAS INSTRUMENTS	

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